

# **Complementary MOSFET Half-Bridge (N- and P-Channel)**

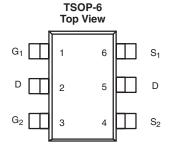
PRODUCT SUMMARY				
	V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	
N-Channel	20	0.300 at V <sub>GS</sub> = 4.5 V	1.4	
		0.410 at V <sub>GS</sub> = 3.0 V	1.2	
P-Channel	- 20	0.640 at V <sub>GS</sub> = - 4.5 V	- 0.96	
		0.980 at V <sub>GS</sub> = - 3.0 V	- 0.78	

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R<sub>a</sub> Tested
- Compliant to RoHS Directive 2002/95/EC

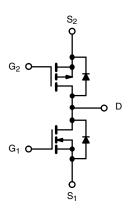






Ordering Information: Si3850ADV-T1-E3 (Lead (Pb)-free)

Si3850ADV-T1-GE3 (Lead (Pb)-free and Halogen-free)



<b>ABSOLUTE MAXIMUM RATINGS</b>	$T_A = 25$ °C, unle	ss otherwise	noted			
Parameter		Symbol	N-Channel	P-Channel	Unit	
Drain-Source Voltage		$V_{DS}$	20	- 20	V	
Gate-Source Voltage		$V_{GS}$	±	7 v		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I_	1.4	- 0.96		
	T <sub>A</sub> = 70 °C	l <sub>D</sub>	1.1	- 0.77	_	
Pulsed Drain Current		I <sub>DM</sub>	3.5	- 2.0	A	
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	0.9	- 0.9		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.08		w	
(Surface Mounted on FR4 Board)	T <sub>A</sub> = 70 °C	' D	0.70			
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 t	°C		

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	N- or P-Channel	Unit		
Maximum Junction-to-Ambient (Surface Mounted on FR4 Board, ± ≤ 10 s)	R <sub>thJA</sub>	115	°C/W		

Note:

Maximum under Steady State condition is 150 °C/W.



		ss otherwise noted		N#:	T	Mari	1112	
Parameter	Symbol	Test Conditions		Min.	Тур.	Max.	Unit	
Static		V V 1 050 A			T			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	N-Ch	0.6		1.5	V	
		$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	P-Ch	- 0.6		- 1.5		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$				± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch			1	- μΑ	
		$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$	P-Ch			- 1		
		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 70 ^{\circ}\text{C}$	N-Ch			10		
		$V_{DS}$ = - 20 V, $V_{GS}$ = 0 V, $T_{J}$ = 70 °C	P-Ch			- 10		
On-State Drain Current <sup>b</sup>	I- c	$V_{DS} = 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	N-Ch	3.0			۸	
	I <sub>D(on)</sub>	$V_{DS} = -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	P-Ch	- 1.5			Α	
Drain-Source On-State Resistance <sup>b</sup>		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 0.5 A	N-Ch		0.240	0.300	Ω	
	B	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 0.5 A	P-Ch		0.510	0.640		
	R <sub>DS(on)</sub>	$V_{GS} = 3.0 \text{ V}, I_D = 0.5 \text{ A}$	N-Ch		0.325	0.410		
		V <sub>GS</sub> = - 3.0 V, I <sub>D</sub> = - 0.5 A	P-Ch		0.780	0.980		
	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 A	N-Ch		1.8		S	
Forward Transconductance <sup>b</sup>		V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 1 A	P-Ch		1.1			
h	V <sub>SD</sub>	I <sub>S</sub> = 0.9 A, V <sub>GS</sub> = 0 V	N-Ch		0.87	1.2	V	
Diode Forward Voltage <sup>b</sup>		I <sub>S</sub> = - 0.8 A, V <sub>GS</sub> = 0 V	P-Ch		- 1.0	- 1.3		
Dynamic <sup>b</sup>	•				I.			
Total Cata Chausa			N-Ch		0.95	1.4		
Total Gate Charge	$Q_g$	N-Channel	P-Ch		1.10	1.7		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 1 \text{ A}$	N-Ch		0.22		nC	
date-oddice onlarge		P-Channel	P-Ch		0.28		nC	
Gate-Drain Charge		$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -1 \text{ A}$	N-Ch		0.24			
	gu		P-Ch		0.26			
Gate Resistance	$R_{g}$		N-Ch		3.5	5.3	Ω	
	9		P-Ch		10.5	16		
Turn-On Delay Time	t <sub>d(on)</sub>	N-Channel	N-Ch P-Ch		8	14	-	
	<u> </u>	$V_{DD} = 10 \text{ V}, R_L = 10 \Omega$	N-Ch		13 16	20 25		
Rise Time	t <sub>r</sub>	$I_D \cong 0.9 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	P-Ch		34	50		
			N-Ch		20	30		
Turn-Off Delay Time	t <sub>d(off)</sub>	P-Channel	P-Ch		18	30	ns	
	<del>                                     </del>	$V_{DD} = -10 \text{ V}, R_L = 10 \Omega$ $I_D \cong -0.9 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$	N-Ch		9	15		
Fall Time	t <sub>f</sub>	D = 0.075, GEN = 7.0 4, rig = 132	P-Ch		18	30		
	t <sub>rr</sub>	I <sub>F</sub> = 0.9 A, dI/dt = 100 A/μs	N-Ch		20	30		
Body Diode Reverse Recovery Tme		I <sub>F</sub> = - 0.9 A, dl/dt = 100 A/μs	P-Ch		25	40		
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = 0.9 A, dI/dt = 100 A/μs	N-Ch		9	15	<del> </del>	
		I <sub>F</sub> = - 0.9 A, dl/dt = 100 A/μs	P-Ch		9	15	nC	

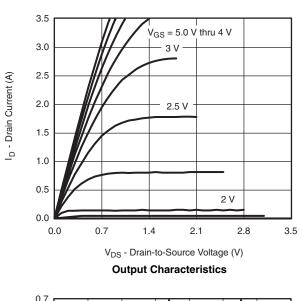
#### Notes:

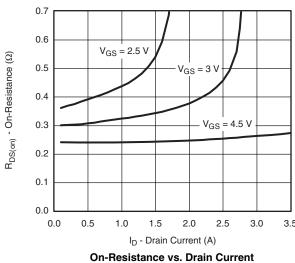
- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.

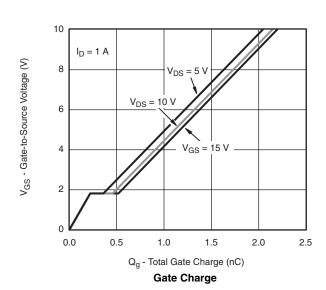
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

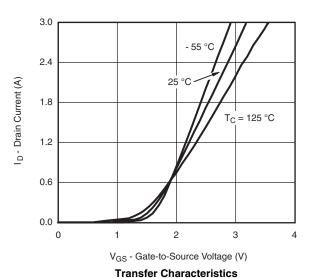


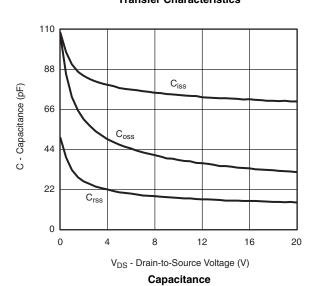
### N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

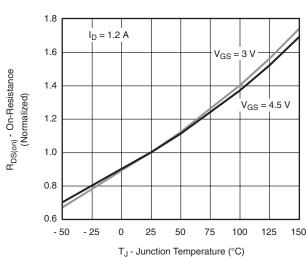






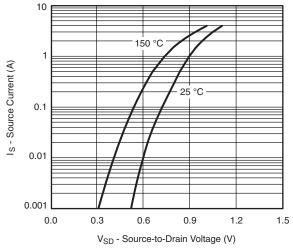




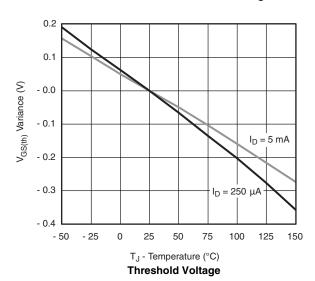


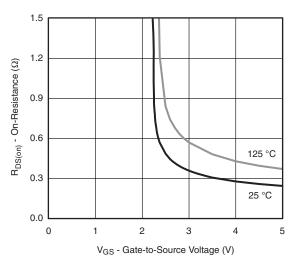
# VISHAY

## N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

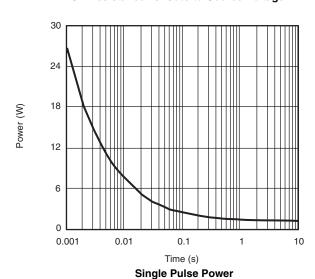


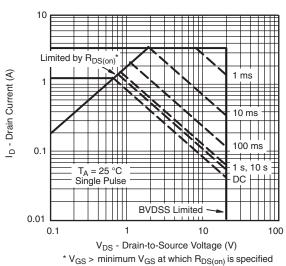
#### Source-Drain Diode Forward Voltage





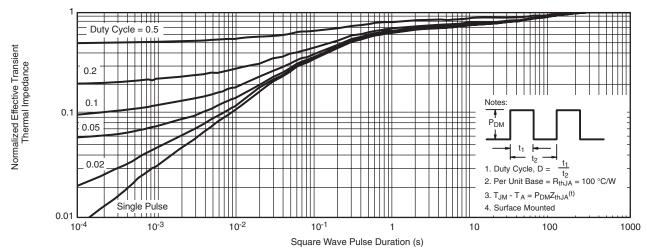
On-Resistance vs. Gate-to-Source Voltage





Safe Operating Area

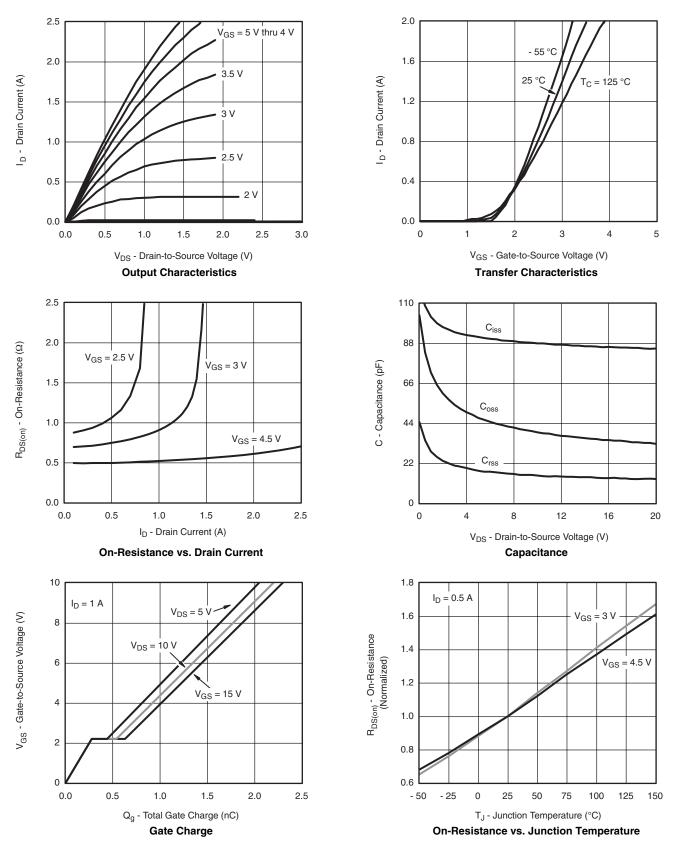
## N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient

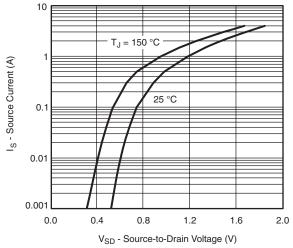
# VISHAY

### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

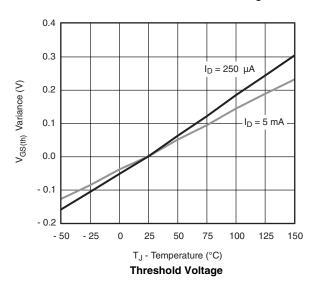


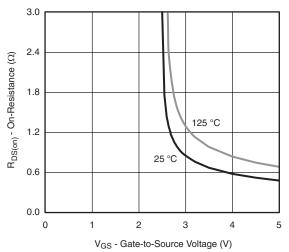


#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

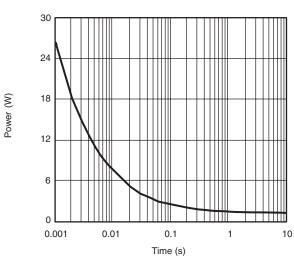


#### Source-Drain Diode Forward Voltage

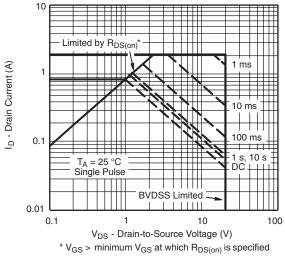




On-Resistance vs. Gate-to-Source Voltage



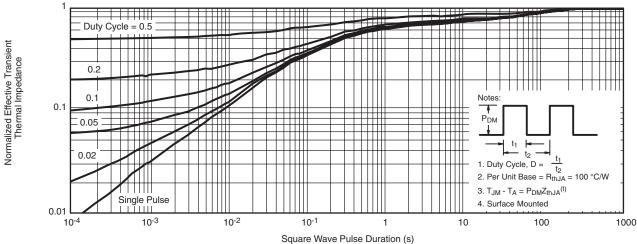
Single Pulse Power vs. Junction-to-Ambient



Safe Operating Area



### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient

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